Abstract:

Method for producing a semiconductor wafer with a polished edge

The invention relates to a method for producing a semiconductor wafer with a polished edge, said method comprising the following steps:
a polishing of at least one side of the semiconductor wafer,
and a polishing of the edge of the polished semiconductor wafer,
wherein the edge is polished in the presence of a polishing agent by means of a polishing cloth containing fixed abrasive.